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(21) International Application Number: PCT/EP97/07155 (22) International Filing Date: 15 December 1997 (15.12.97) (30) Priority Data: 08/767,057 16 December 1996 (16.12.96) US (71) Applicant: SHELL INTERNATIONALE RESEARCH MAATSCHAPPIJ B.V. [NL/NL]; Carel van Bylandtlaan 30, NL-2596 HR The Hague (NL). (72) Inventors: IYER, Shridhar, Ratnaswamy; 16930 Ascot Meadow Drive, Sugar Land, TX 77479 (US). WONG, Pui, Kwan; 6431 Mercer Street, Houston, TX 77005 (US).	(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, GW, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>	
(54) Title: DIE ATTACH ADHESIVE COMPOSITIONS (57) Abstract A novel thermally reworkable die attach adhesive composition for attaching a semiconductor device to a substrate is provided. The composition comprises (a) a thermally reworkable cross-linked resin produced by reacting at least one dienophile having a functionality greater than one and at least one 2,5-dialkyl substituted furan-containing polymer, and (b) at least one thermally and/or electrically conductive material present in an effective amount up to 90 % by weight of the die attach composition to provide a conducting medium.		